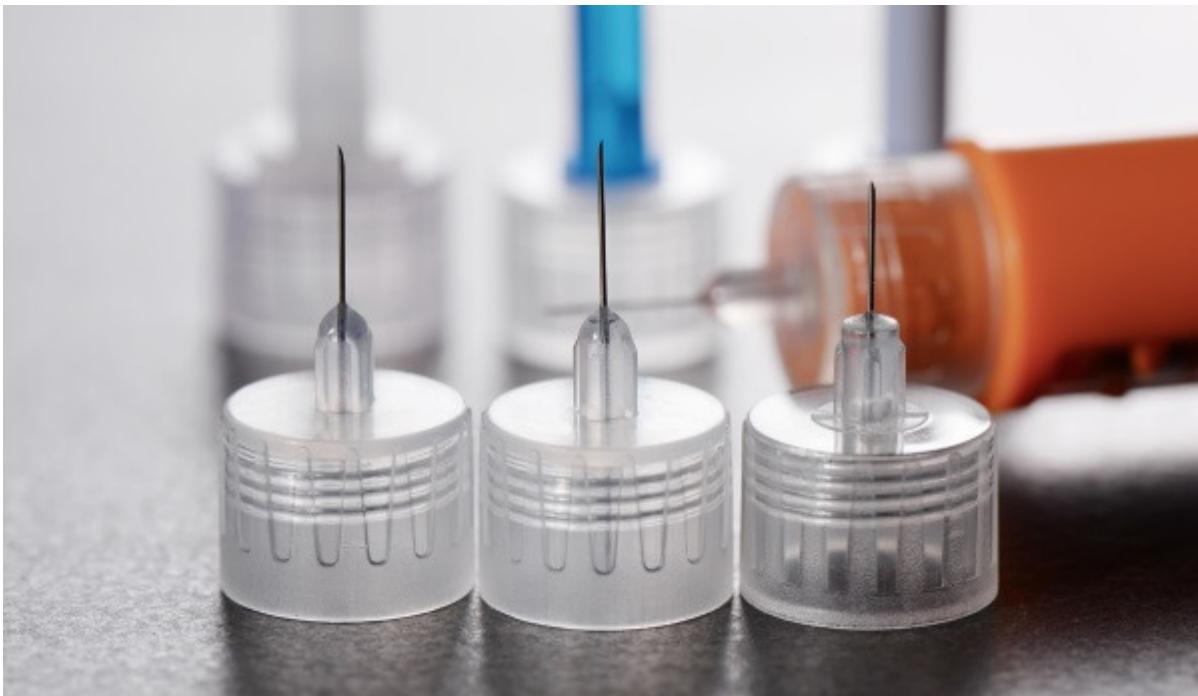


Next generation needle bonding adhesive

Our partners Dymax have recently introduced [Dymax 1406-M](#), a next generation **needle bonding adhesive** for manufacturers looking to switch to [UV LED curing](#) in small gauge needle applications. It provides superior bonding performance on the reduced surface area of smaller cannulas, even after aging and sterilization, to reduce the possibility of cannula substrate failure. Optimized for 385nm LED curing, Dymax 1406-M allows for tighter standard deviations and enables small gauge needle manufacturers to enjoy the benefits of LED curing without sacrificing speed or cured mechanical properties.



Next generation needle bonding adhesive

Supplied by:



INTERTRONICS

12a Station Field Industrial Estate, Banbury Road, Kidlington

Oxfordshire England OX5 1JD

t 01865 842842 e info@intertronics.co.uk

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